

## Features

- Ideal for automated placement
- Low forward voltage drop
- Low leakage current
- Meets environmental standard MIL-S-19500D
- Moisture sensitivity: level 1, per J-STD-020
- Solder dip 275°C, 10s
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC



DO-214AA (SMB)

## Applications

For use in general purpose rectification of lighting, power supplies, inverters, converters and freewheeling diodes for consumer, automotive and telecommunication applications.

## Mechanical Data

- Case: DO-214AA, molded epoxy body, epoxy meets UL 94V-0 flammability rating
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22B-106
- Polarity: Laser band denotes cathode band

## Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	GSL310B	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	100	V
Maximum RMS Voltage	V <sub>RMS</sub>	70	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	100	V
Maximum Average Forward Rectified Current @ T <sub>L</sub> (See Fig.1)	I <sub>F(AV)</sub>	3.0	A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	80	A
Maximum Thermal Resistance from Junction to Ambient <sup>1</sup>	R <sub>θJA</sub>	72	°C/W
Maximum Thermal Resistance from Junction to Terminal <sup>2</sup>	R <sub>θJT</sub>	22	
Typical Thermal Resistance from Junction to Case	R <sub>θJC</sub>	37	
Operating Junction Temperature Range	T <sub>J</sub>	-55 to +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

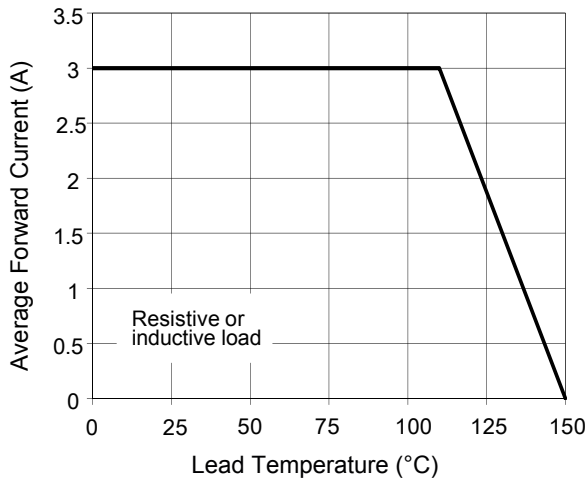
## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	GSL310B	Unit
Maximum Instantaneous Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =3A	0.75	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I <sub>R</sub>	T <sub>A</sub> =25°C	0.15	mA
Typical Junction Capacitance	C <sub>J</sub>	4.0V, 1MHz	220	pF

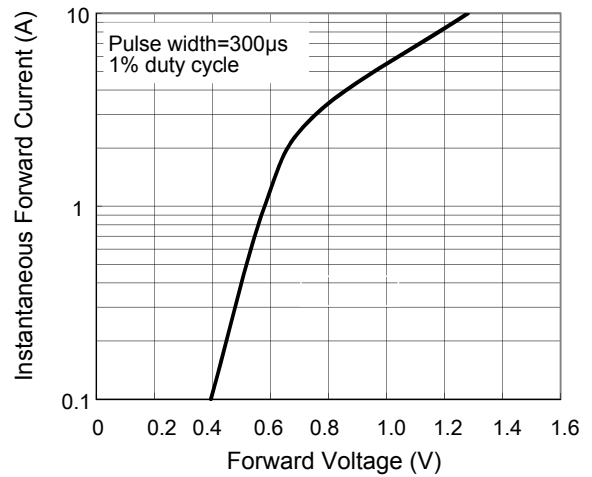
Notes:

1. Thermal resistance from junction to ambient, 0.276x0.276 inch (7.0x7.0mm) copper pads to each terminal.
2. Thermal resistance from junction to terminal, 0.276x0.276 inch (7.0x7.0mm) copper pads to each terminal.

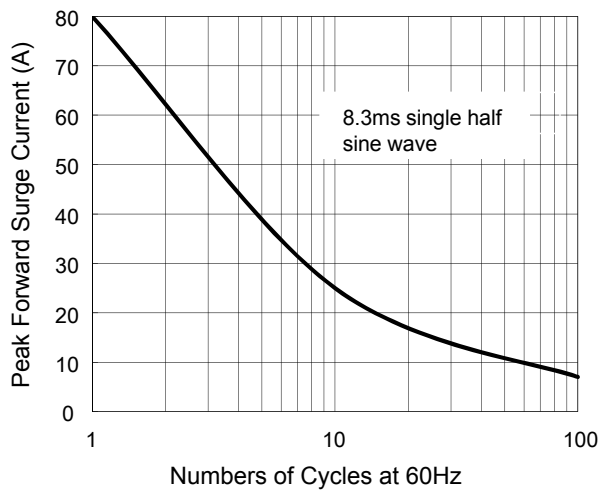
## Ratings and Characteristics Curves ( $T_A=25^\circ\text{C}$ unless otherwise noted)



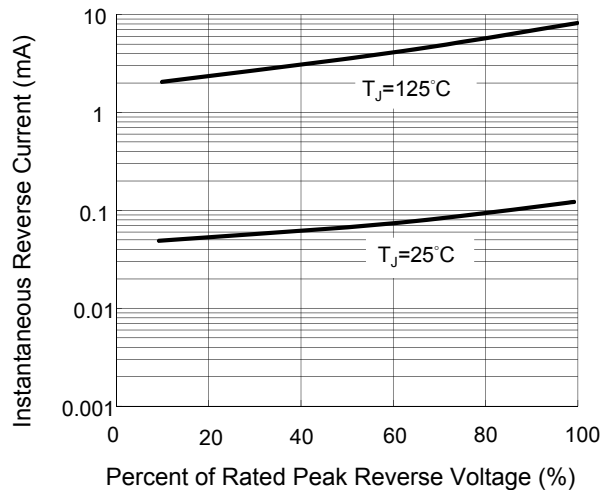
**Figure 1. Forward Current Derating Curve**



**Figure 2. Typical Forward Characteristics**

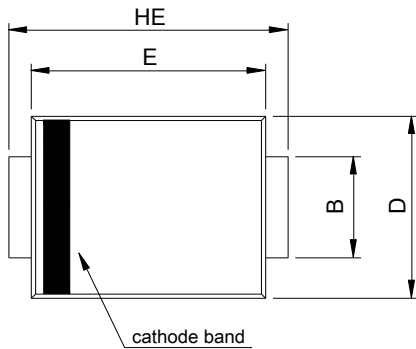


**Figure 3. Maximum Non-Repetitive Peak Surge Current**

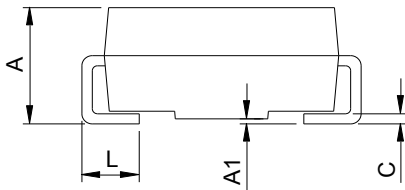


**Figure 4. Typical Reverse Characteristics**

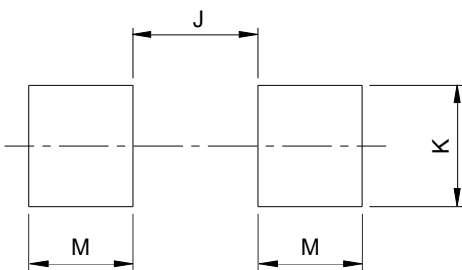
## Package Outline Dimensions (SMB)



SMB (DO-214AA)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.95	2.65	0.077	0.104
A1	0.00	0.20	0.000	0.008
B	1.95	2.20	0.077	0.087
C	0.15	0.31	0.006	0.012
D	3.30	3.95	0.130	0.156
E	4.06	4.60	0.160	0.181
HE	5.10	5.60	0.201	0.220
L	0.76	1.60	0.030	0.063



## Recommended Pad Layout



SMB Recommended Pad Layout (Reference Only)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.60	-	0.102
K	2.20	-	0.087	-
M	1.80	-	0.071	-

## Order Information

Device	Package	Marking	Carrier	Quantity
GSL310B	SMB	SL310B	Tape & Reel	3,000 pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)